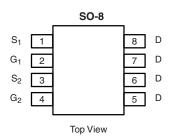




Complementary MOSFET Half-Bridge (N- and P-Channel)

PRODUCT SUMMARY							
	V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A)				
N-Channel	20	0.020 at V _{GS} = 4.5 V	9.1				
		0.030 at V _{GS} = 2.5 V	7.5				
P-Channel	- 20	0.060 at V _{GS} = - 4.5 V	- 5.3				
	- 20	0.100 at V _{GS} = - 2.5 V	- 4.1				



Ordering Information: Si4500BDY-T1-E3 (Lead (Pb)-free)

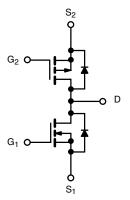
Si4500BDY-T1-GE3 (Lead (Pb)-free and Halogen-free)

FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET[®] Power MOSFET
- Compliant to RoHS Directive 2002/95/EC







ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, unless otherwise noted								
Parameter		N-C		Channel	P-Channel			
		Symbol	10 s	Steady State	10 s	Steady State	Unit	
Drain-Source Voltage		V_{DS}	20		- 20		V	
Gate-Source Voltage		V_{GS}	± 12		± 12		V	
Continuous Drain Current (T _J = 150 °C) ^{a,b}	T _A = 25 °C	- I _D	9.1	6.6	- 5.3	- 3.8	_	
	T _A = 70 °C		7.3	5.3	- 4.9	- 3.1		
Pulsed Drain Current		I _{DM}		30	- 20		Α	
Continuous Source Current (Diode Conduction) ^{a,b}		I _S	2.1	1.1	- 2.1	- 1.1		
Maximum Power Dissipation ^{a,b}	T _A = 25 °C	P _D	2.5	1.3	2.5	1.3	W	
	T _A = 70 °C		1.6	0.8	1.6	0.8		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150				°C	

THERMAL RESISTANCE RATINGS									
			N-Channel		P-Channel				
Parameter	Symbol	Тур.	Max.	Тур.	Max.	Unit			
Manian un lunation to Ambiant	t ≤ 10 s	R _{thJA}	40	50	41	50			
Maximum Junction-to-Ambient ^a	Steady State	' 'thJA	75	95	75	95	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	20	22	23	26			

Notes:

a. Surface Mounted on FR4 board.

b. $t \le 10 \text{ s}$.

Si4500BDY

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Parameter Symbol		Test Conditions	Min.	Typ. ^a	Max.	Unit		
Static			<u> </u>					
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$ N		0.6		1.5	V	
Gate Threshold Voltage		$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	P-Ch	- 0.6		- 1.5	v	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$	N-Ch			± 100	nA	
	-033		P-Ch			± 100		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 20 V, V _{GS} = 0 V	N-Ch			1	1	
		V _{DS} = - 20 V, V _{GS} = 0 V	P-Ch			- 1	μΑ	
	D33	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$	N-Ch			5		
		$V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$	P-Ch			- 5		
On-State Drain Current ^b	I _{D(on)}	$V_{DS} = 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	N-Ch	30			A	
		V _{DS} = - 5 V, V _{GS} = - 4.5 V	P-Ch	- 20				
Drain-Source On-State Resistance ^b	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 9.1 \text{ A}$	N-Ch		0.016	0.020		
		V _{GS} = - 4.5 V, I _D = - 5.3 A	P-Ch		0.048	0.060		
		$V_{GS} = 2.5 \text{ V}, I_D = 3.3 \text{ A}$	N-Ch		0.024	0.030	Ω	
		V _{GS} = - 2.5 V, I _D = - 1 A	P-Ch		0.082	0.100		
Forward Transconductance ^b	_	V _{DS} = 15 V, I _D = 9.1 A	N-Ch		29			
	9 _{fs}	V _{DS} = - 15 V, I _D = - 5.3 A	P-Ch		11		S	
	V _{SD}	I _S = 2.1 A, V _{GS} = 0 V	N-Ch		0.8	1.2	.,	
Diode Forward Voltage ^b		I _S = - 2.1 A, V _{GS} = 0 V	P-Ch		- 0.8	- 1.2	V	
Dynamic ^a		,			'	'		
Total Cata Charge	0		N-Ch		11	17		
Total Gate Charge	Q_g	N-Channel $V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 9.1 \text{ A}$	P-Ch		6.0	9	nC	
Gate-Source Charge	Q_{qs}	V _{DS} = 10 V, V _{GS} = 4.5 V, I _D = 9.1 A	N-Ch		2.5			
Cate Course Charge	⊶gs	P-Channel	P-Ch		1.3			
Gate-Drain Charge	Q _{gd}	$V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -5.3 \text{ A}$	N-Ch		3.2			
			P-Ch		1.6	50		
Turn-On Delay Time	t _{d(on)}	N-Channel	N-Ch P-Ch		35	50 30		
		$V_{DD} = 10 \text{ V}, R_L = 10 \Omega$	N-Ch		20 50	80	_	
Rise Time	t _r	$I_D\cong$ 1 A, V_{GEN} = 10 V, R_g = 6 Ω	P-Ch		35	60		
		D Ohannal	N-Ch		31	50		
Turn-Off Delay Time	t _{d(off)}	P-Channel $V_{DD} = -10 \text{ V}, R_{L} = 10 \Omega$	P-Ch		55	85	ns	
Fall Time	+.	$I_D \cong -1$ A, $V_{GEN} = -4.5$ V, $R_g = 6 \Omega$	N-Ch		15	30		
Fall Time	t _f		P-Ch		35	60		
Source-Drain Reverse Recovery Time	t _{rr}	I _F = 2.1 A, dI/dt = 100 A/μs N-Ch			30	60		
Jource-Dialit neverse necovery Time		I _F = - 2.1 A, dl/dt = 100 A/μs	P-Ch		25	50		

Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Guaranteed by design, not subject to production testing.

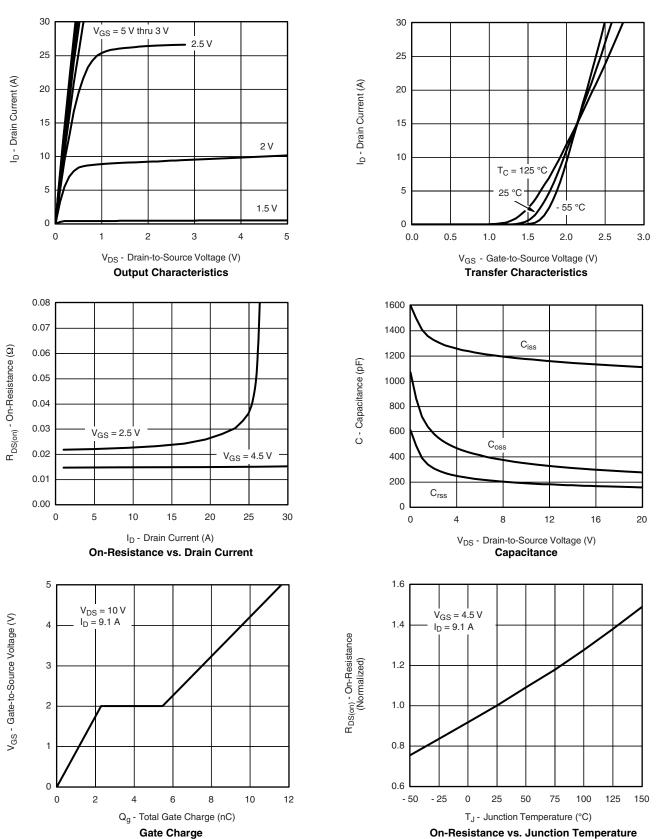
b. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.







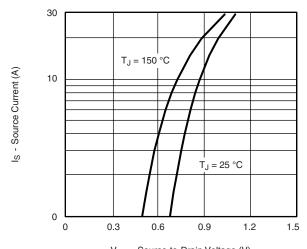
N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



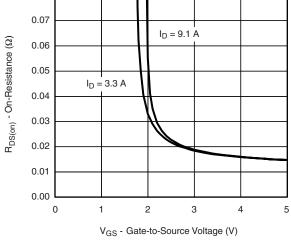
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N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

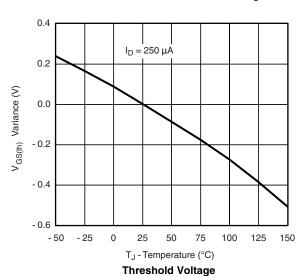


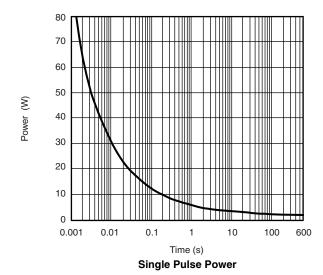
V_{SD} - Source-to-Drain Voltage (V) **Source-Drain Diode Forward Voltage**

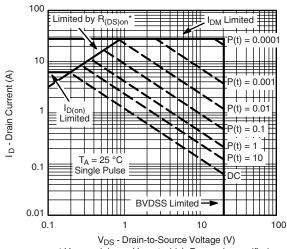


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On-Resistance vs. Gate-to-Source Voltage







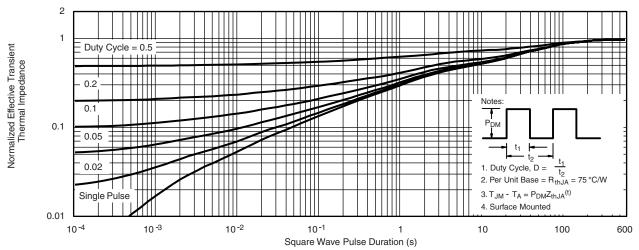
 v_{DS} - Drain-to-Source Voltage (V)

* v_{GS} > minimum v_{GS} at which v_{DS} (m) is specified

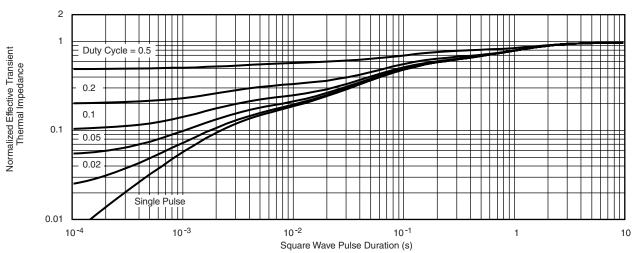
Safe Operating Area



N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient

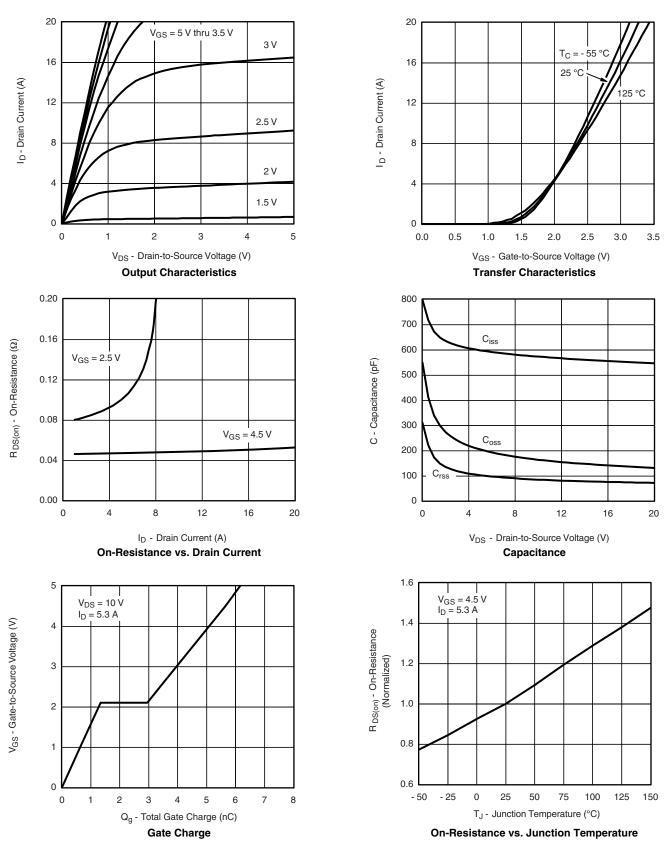


Normalized Thermal Transient Impedance, Junction-to-Foot

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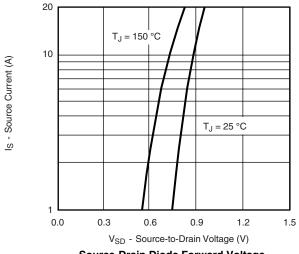
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P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

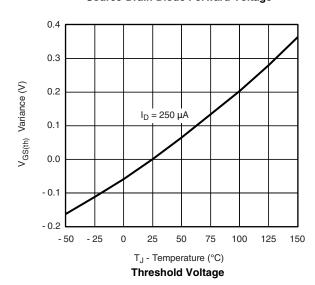


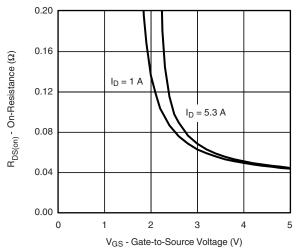


P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

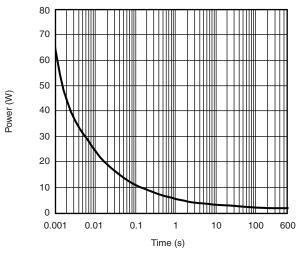




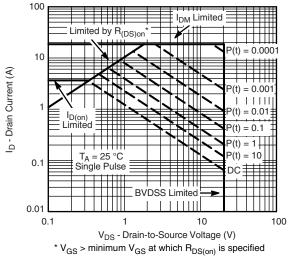




On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power

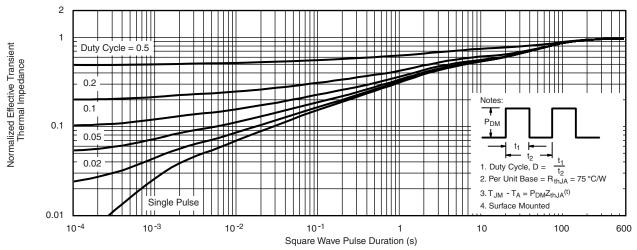


Safe Operating Area

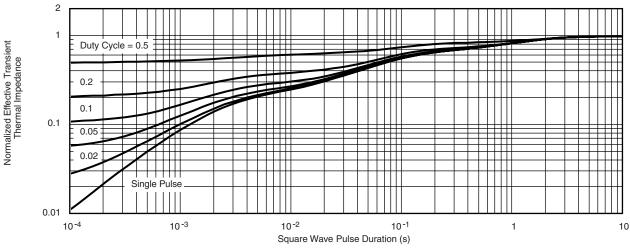
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P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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